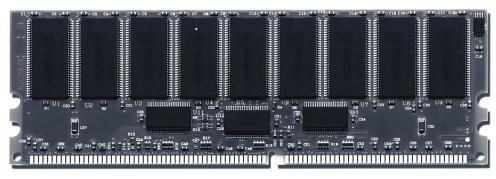




HCD DDR DIMM Products with x4, x8 and x16 Devices

modular subsystems and high frequency solutions





DDR DIMM modules (registered & unbuffered)

Modules not shown actual size

Product Overview

FEATURES

High Speed PC1600 and PC2100 DDR Modular Subsystems

JEDEC compliant

Two data accesses per clock cycle

Auto refresh and self refresh modes

Serial Presence Detect (SPD)

 V_{DD} = +2.5 $V \pm 0.2V$

Addressing high frequency module requirements, HCD offers a complete line of JEDEC compliant DDR DIMM and SO-DIMM products in both PC1600 and PC2100 speed grades. In a system with a 64-bit wide memory bus, DDR modules can reach a peak bandwidth of 2.13GB per second at 266MHz as compared to mainstream PC133 (SDRAM) modules, which offer a performance of 1.06GB per second.

HCD's DDR products are well suited for a broad range of applications, which include the server and network markets where the high memory capacity and speed are necessary to meet the performance demands of these products. The performance improvement achieved with DDR technology helps to ensure that memory stays in step with the constantly increasing performance of microprocessors.

Incorporating superior design and manufacturing control, HCD's products are highly reliable with proven system compatibility. In line with HCD's strong commitment to quality, all HCD modules are 100% tested to ensure performance and reliability.

HCD's comprehensive line of high performance DDR products comes in a variety of configurations and form factors to support today's diverse market driven requirements. HCD continuously adds to and improves upon its current line to provide innovative solutions for the ever-changing, competitive landscape.

HCD's DDR products are available in both Registered and Unbuffered configurations in either PC1600 or PC2100 speed grades. Module densities range from 128MB up to 1GB, using x4, x8 or x16 devices.

HCD DDR DIMM Product Guide

**See Ordering Information for part numbering guide

PRODUCT	E/N	Speed	Capacity	Model Number
Unbuffered DDR DIMM				
16Mx8 chip / 16Mx64 DIMM	Non	PC2100	128MB	HD41808U4SA
16Mx8 chip / 32Mx64 DIMM	Non	PC2100	256MB	HD51816U4SA
Registered DDR DIMM				
32Mx4 chip / 32Mx72 DIMM	ECC	PC2100	256MB	HD52418R4SA
32Mx4 chip / 32Mx72 DIMM	ECC	PC2100	256MB	HD52418R4S2
32Mx8 chip / 64Mx72 DIMM	ECC	PC2100	512MB	HD62818R8SA
32Mx8 chip / 64Mx72 DIMM	ECC	PC2100	512MB	HD62818R8S2
64Mx4 chip / 128Mx72 DIMM (stacked)	ECC	PC2100	1GB	HD72436R8SA
64Mx4 chip / 128Mx72 DIMM (stacked)	ECC	PC2100	1GB	HD72436R8S2
Unbuffered DDR SO-DIMM				
16Mx16 chip / 16Mx64 SO-DIMM	Non	PC2100	128MB	HE41604U4SA
16Mx16 chip / 16Mx64 SO-DIMM	Non	PC2100	128MB	HE41604U4S2
16Mx16 chip / 16Mx72 SO-DIMM	ECC	PC2100	128MB	HE42604U4SA
16Mx16 chip / 16Mx72 SO-DIMM	ECC	PC2100	128MB	HE42604U4S2

^{**}Other speed-grades and/or configurations available upon request.

ORDERING INFORMATION

	DDR Part Numbering System														
Name	Type/Foot Print	Module	Module Bus	Component	# of	Register	Refresh/	Cycle Time	CAS Latency	-	Fab	PCB Design	Device Package	Device	Device
		Address	Width	Data Width	Devices		Internal Bank							Vendor	Rev.
Н	D = DDR DIMM	3 = 8M	1 = 64	4 = x4	02 = 2	U = Unbuffered	Standard	6 = 6ns 166MHz	1 = CL1		T = TW	B = IBM	3 = 300mil TSOP	A = NanYa	Α
	E = DDR SO-DIMM	4 = 16M	2 = 72	8 = x8	03 = 3	R = Registered	1 = 1K/2bk	7 = 7ns 142MHz	2 = CL2		C = Celes	H = HCD	4 = 400mil TSOP	B = IBM	В
	U = Custom	5 = 32M		6 = x 16	04 = 4		2 = 2K/4bk	8 = 8ns 125MHz	3 = CL3		S = Sel	M = Micron	6 = 600mil TSOP	F = Infineon	С
		6 = 64M		2 = x32	05 = 5		3 = 2K/2bk	A = 10ns 100MHz	5 = CL2&3				C = CSP	K = OKI	D
		7 = 128M			08 = 8		4 = 4K/4bk	C = 12ns 83MHz	A = CL2.5					M = Micron	
					09 = 9		5 = 4K/2bk	F = 15ns 66MHz	B = CL2&2.5					N = NEC	
					16 = 16		8 = 8K/4bk	G = 7.5ns 133MHz						S = Samsung	
					18 = 18		6 = 16K/4bk	H = CL2=10, CL2.5=7.5						T = Toshiba	
					32 = 32		Low Power	P = PC100						Y = Hy undai	
					36 = 36		A = 1K/2bk	Q = PC133							
							B = 2K/4bk	R = PC1600							
							C = 2K/2bk	S = PC2100							
							D = 4K/4bk								
							E = 4K/2b								
							F = 8K/4bk								
							G = 16K/4bk								
							Self Refresh								
							L = 1K/2bk								
							M = 2K/4bk								
							N = 2K/2bk								
							P = 4K/4bk								
							Q = 4K/2bk								
							R = 8K/4bk								

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www.hcdcorp.com

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